

Warsaw University of Technology, Poland, 12.08.2019

Dear IEEE IES Students and Young Professionals (S&YP),

Thank you for your excellent contribution and congratulation! It is a great honor to announce the Awardees of the IES-SYPA competition for the **IEEE HSI 2019**.

Important note for the S&YP that applied for the IES-SYPA:

In this year for the **IEEE ETFA 2019** we have received **11** applications for the IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE (IES-SYPA). The average weighted score is **6.51**. We would like to announce **4 IES-SYPA** (recognition diploma plus up-to **USD 2000** travel costs reimbursement) recipients (see the table below).

transaction	applicant	manuscript title	all authors
EF-006459	Ivan Pisa, Universitat Autònoma de Barcelona, Spain, ivan.pisa@uab.cat	ANN-based Internal Model Control strategy applied in the WWTP industry	Ivan Pisa, Antoni Morell, Jose Lopez Vicario, Ramon Vilanova
EF-005045	Geeta Yadav, Research Scholar, India, geeta@cse.iitd.ac.in	Assessment of SCADA System Vulnerabilities	Geeta Yadav, Kolin Paul
EF-000078	Junhui Jiang, Department of Electronic Systems Engineering Hanyang University, Korea (South), 0229ender@gmail.com	A Simulation Model for Time-sensitive Networking (TSN) with Experimental Validation	Junhui Jiang, Yuting Li, Seung Ho Hong, Mengmeng Yu, Aidong Xu, Min Wei
EF-005584	Muhammad Rusyadi Ramli, Department of IT Convergence Engineering, Kumoh National Institute of Technology, Korea (South), muhammadrusyadi@kumoh.ac.kr	Bio-inspired Service Provisioning Scheme for Fog-based Industrial Internet of Things	Muhammad Rusyadi Ramli, Philip Tobianto Daely, Jae Min Lee, Dong-Seong Kim

**Mandatory requirements and important notes:**

- I. **Please take into account that IEEE IES must follow general rules of IEEE related with OFAC Sanctions Programs to learn more please see <https://www.ieee.org/about/compliance/ofac/sanctions.html>. For more details, you may ask The Legal and Compliance Department available to assist with reviewing any questions that you may have with respect to OFAC or other compliance matters and can be reached at [compliance@ieee.org](mailto:compliance@ieee.org).**
- II. You will have to be active during the conference as a volunteer. For tasks and more details, please contact Secretary of ETFA 2019 at [etfa2019@unizar.es](mailto:etfa2019@unizar.es) AND Cristian Mahulea, Gen. Chair of ETFA 2019 at [cmahulea@unizar.es](mailto:cmahulea@unizar.es).
- III. **Students and Young Professionals** must present their project in a 3-minutes speech (3Ms) accompanied by a 3-minute video clip and with hardware demonstration (if applicable).
- IV. You will receive the SYPA result by email from Marek Jasinski, and then, you will receive the full instruction on how to prepare that video and speech for 3Ms IES-SYPA Speech Video Session and the submission deadline from Hani Vahedi ([hani.vahedi@ieee.org](mailto:hani.vahedi@ieee.org)).
- V. Your video will be uploaded on IES YouTube Channel, Facebook Page, and **IEEE Collabratec** to be available during the conference. Important:
  - a. Please open an **IEEE Collabratec** account with your IEEE login information, and you will receive the information about how to join the IES-SYPA group.
  - b. Once your video is approved and uploaded to the IES YouTube, then you should post it to the IEEE Collabratec Group and to the Facebook event page.
- VI. Please be sure that during the conference **you should have your video available offline** and the hardware demonstration (if applicable). **(Time and place for 3Ms presentation will be announced by the General Chair of the Conference).**



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- VII. The diplomas for the IES-Student Paper Travel Assistance (IES-SYPA) will be presented during the conference at the Gala Dinner.
- VIII. **Take photos during the conference and submit them on your and IES Facebook profile.**
- IX. Submit your expenses report via Concur:  
In Concur, please select the following expense report purpose (ERP).  
Expense Report Purpose Lvl 1 - Technical Activities Societies  
Expense Report Purpose Lvl 2 - Industrial Electronics Society  
Expense Report Purpose Lvl 3 - VP-Membership Student Activities  
Expense Report Purpose Lvl 4 - YPROS (this is the only option available to select)  
**If you have further questions, please check:**  
<http://www.ieee-ies.org/members/treasurer-information>  
<http://www.ieee-ies.org/members/treasurer-information/31-members/treasurer/238-fags,-treasurer-info>  
IES operating unit team contact is Matt LaFleur.
- X. PLEASE NOTE THAT IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE is consist of:  
- Recognition Diploma and  
- up to USD **2000** travel cost reimbursements.
- XI. You can find all the necessary information on Industry Electronics Society websites:  
<https://www.facebook.com/IndustrialElectronicsSociety/>  
<http://www.ieee-ies.org/SYP>  
<https://www.youtube.com/channel/UCKg8GNii0Q-ieXE56AXosGg>

On behalf of the IEEE IES-SYPA Competition Jury:

*IEEE IES President Xinghuo Yu, IES Treasurer Milos Manic, and IES President-Elect Terry Martin,  
Vice President for Conference Activities Juan José Rodríguez Andina,  
Vice President for Membership Activities Yousef Ibrahim,  
Conference General Chair: Antoni Grau,  
Web & Information Committee: Andres A. Nogueiras Melendez, Aleksander Malinowski,  
Ad-Hoc committee related to IEEE OFAC Sanctions Programs:  
Gus Wagner Director, Technical Activities Operations and Society Support Services IEEE Technical Activities.  
Matt LaFleur Technical Community Program Coordinator IEEE Technical Activities.  
and Young Professional & Student Activity Committee: Marek Turzynski, Hani Vahedi, Marek Jasinski.*

*Congratulations and Good Luck,  
Chair of the IEEE IES Young Professional & Student Activity Committee,  
Marek Jasinski*



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